

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

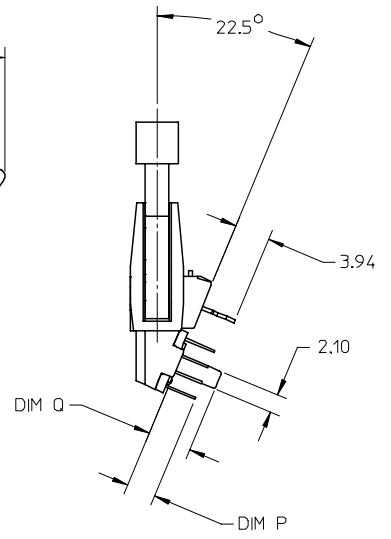
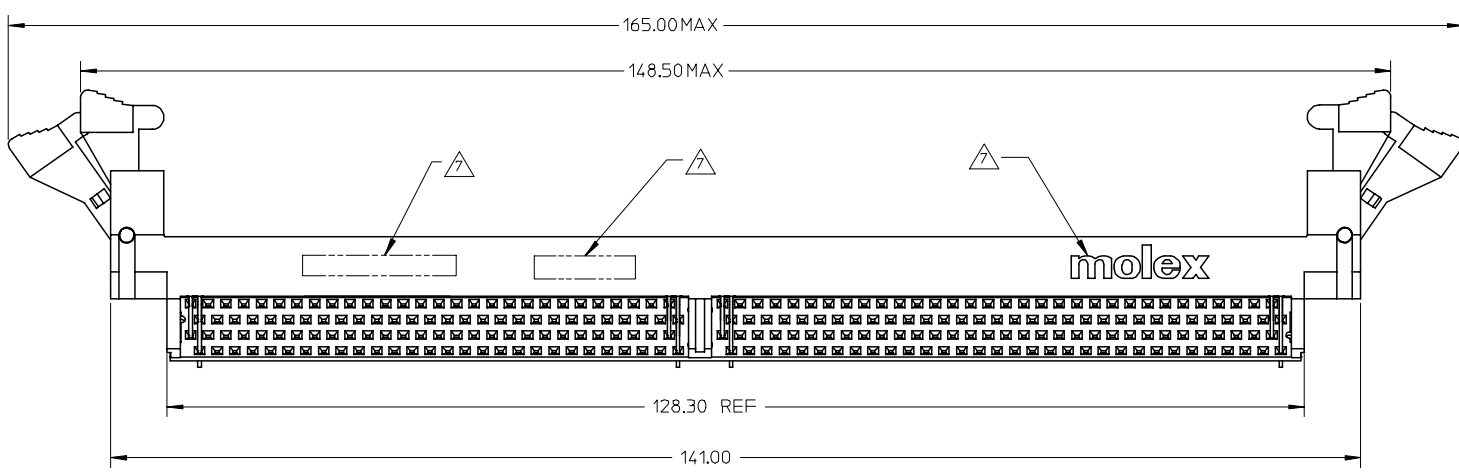
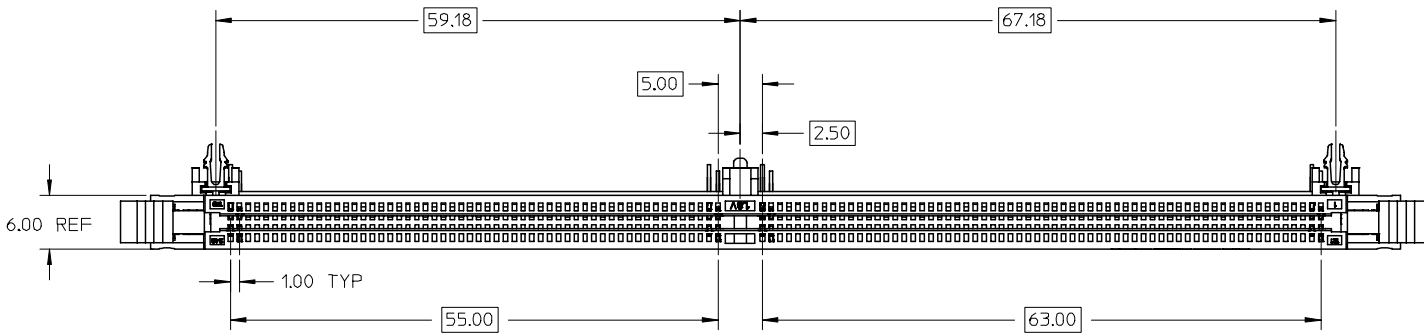
C

B

B

A

A



- NOTES :
- MATERIALS : HOUSING, BASEPLATE AND LATCH.
- HIGH TEMP THERMOPLASTIC, UL94-0.
TERMINALS & FORKLOCK - COPPER ALLOY.
 - PLATING : CONTACT AREA - SEE TABLE IN SHEET 5.
SOLDERTAIL - SEE TABLE IN SHEET 5.
 - CARD SLOT ACCEPTS 1.27+/-0.10MM MODULE THICKNESS
(MEASURED OVER PC PADS).
 - REFER TO PRODUCT SPECIFICATION , PS-87916-001 FOR
PERFORMANCE SPECIFICATION.
 - RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
 - PRODUCT SHALL BE PACKED IN TRAY.
- ▲ MOLEX LOGO, DATE CODE & PART NUMBER INDICATED ON HOUSING.

ADDED OPTION EC NO: S2008-0329 2007/10/24 DRWN:CTEH 2007/10/24 CHKD:TYANG01 2007/10/25 APPR:SHLENI	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG				
				4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	CHECKED BY MLONG	DATE 2004/06/11	MOLEX MOLEX INCORPORATED			
				ANGULAR ± 5 °	APPROVED BY GGLEE	DATE 2004/06/11	DOCUMENT NO. SD-87916-001	SHEET NO. 1 OF 5		
A1	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

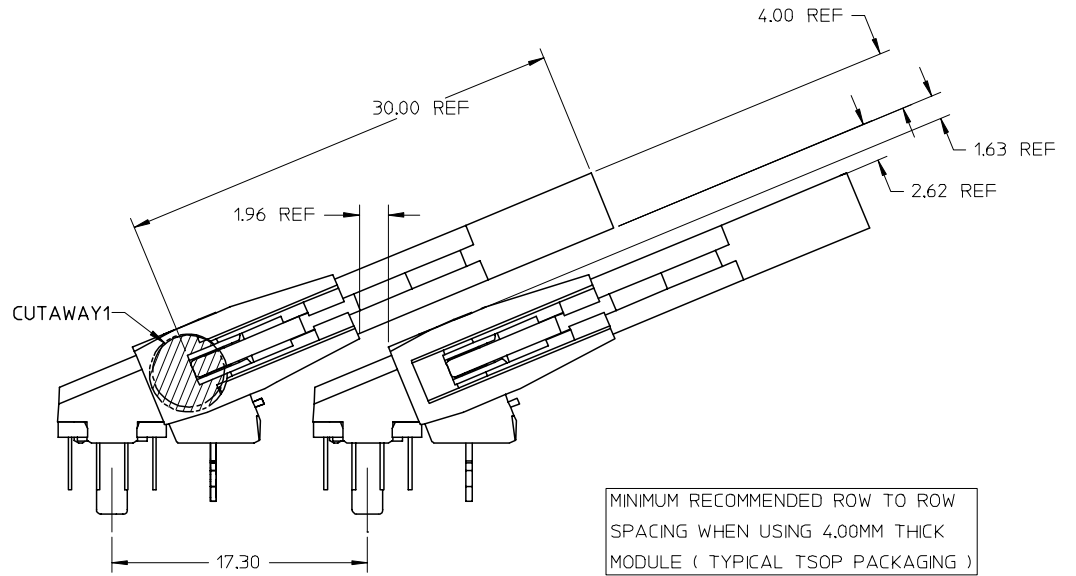
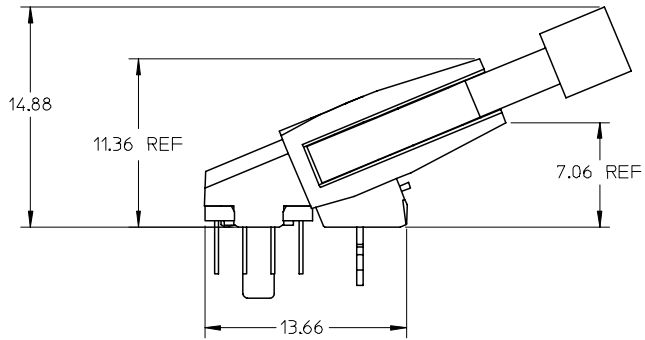
E

D

C

B

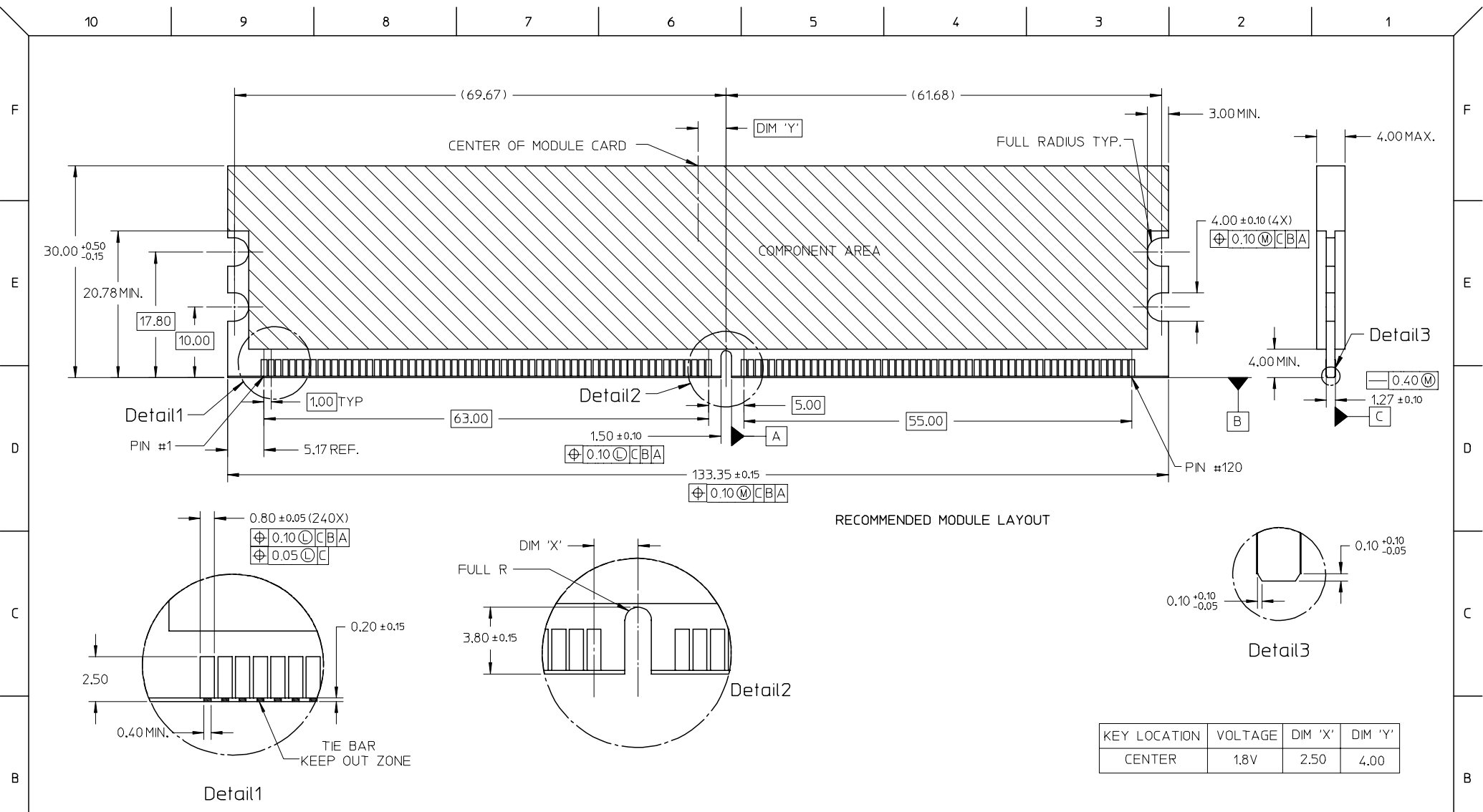
A



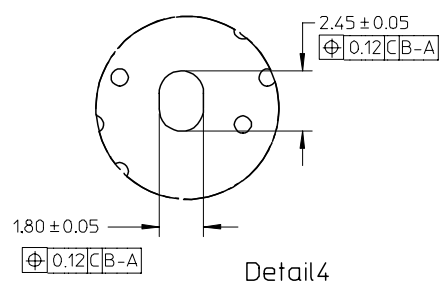
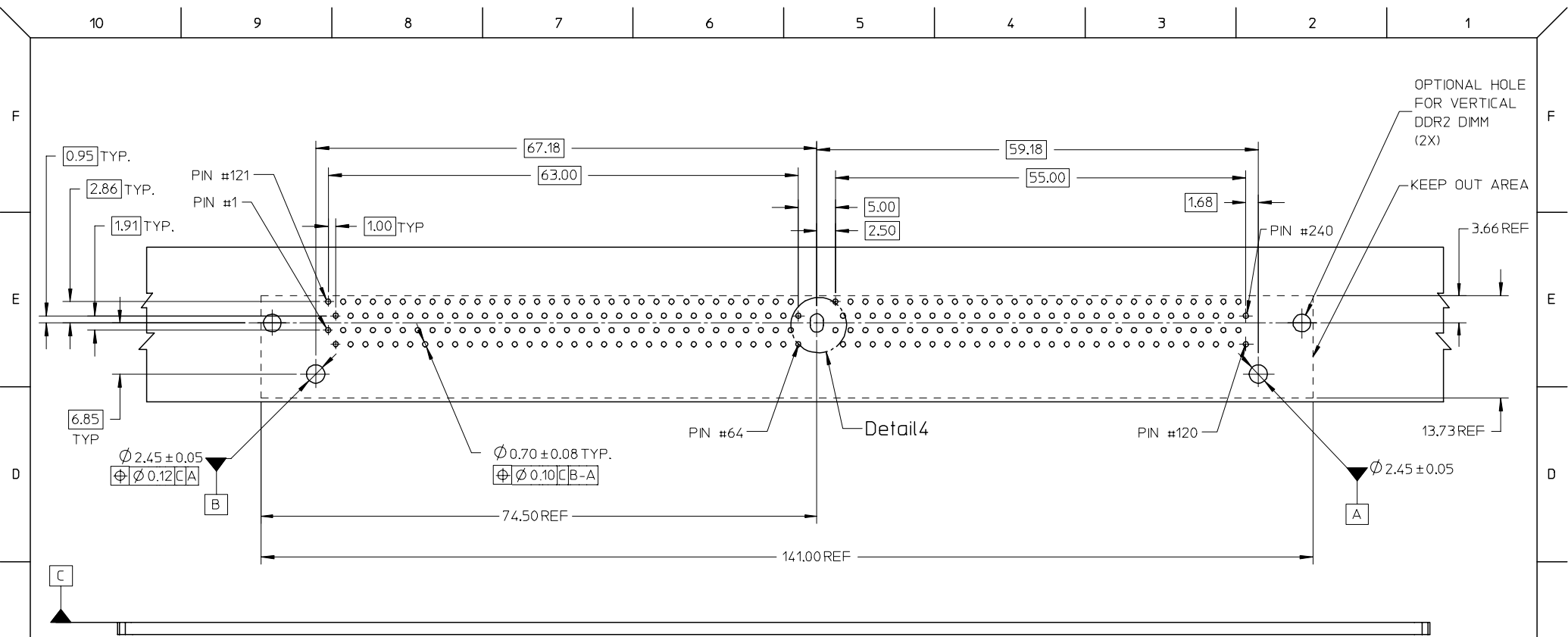
MINIMUM RECOMMENDED ROW TO ROW SPACING WHEN USING 4.00MM THICK MODULE (TYPICAL TSOP PACKAGING)

ADDED OPTION EC NO: S2008-0329 DRWN: CTEH CHKD: TYANG01 APPR: SILENI	2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG				
			4 PLACES	± ---	± ---	CHECKED BY	DATE					
			3 PLACES	± ---	± ---	APPROVED BY MLONG		DATE 2004/06/11	MOLEX INCORPORATED			
2 PLACES	± 0.25	± ---	APPROVED BY GGLEE		DATE 2004/06/11							
1 PLACE	± ---	± ---	ANGULAR ± 5 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
A1	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87916-001		2 OF 5				
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION												

9 8 7 6 5 4 3 2 1



ADDED OPTION EC NO: S2008-0329 DRWN: CTEH CHKD: TYANG01 APPR: SILENI	2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY	DATE	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG		
			4 PLACES	± ---	± ---	JTAN	2004/05/11			
			3 PLACES	± ---	± ---	CHECKED BY	DATE			
2 PLACES	± 0.25	± ---	MLONG	2004/06/11	APPROVED BY GGLEE 2004/06/11		MOLEX INCORPORATED			
1 PLACE	± ---	± ---								
			ANGULAR ± 5 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		SD-87916-001		3 OF 5			



ADDED OPTION EC NO: S2008-0329 DRWN: CTEH CHKD: TYANG01 APPR: SILENI	2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	mm INCH	DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG	MOLEX INCORPORATED		SHEET NO. 4 OF 5
A1	REV	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MATERIAL NO.	DOCUMENT NO. SD-87916-001	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

C

B

B

A

A

PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'O'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING
87916-0001	1.8V	2.79	3.18	1.57	0.76µM/ 30µ" GOLD OVER 1.27µM/ 50µ" MIN NICKEL	2.54µM/ 100µ" MIN. TIN OVER 1.27µM/ 50µ" MIN NICKEL
87916-0011		3.18	4.83	2.36		
87916-0111		4.00		3.20		

ADDED OPTION EC NO: S2008-0329 DRWN: CTEH CHKD: TYANG01 APPR: SILENI	2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ▽=0	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
					mm	INCH	DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG	
	4 PLACES			± ---	± ---	± ---	CHECKED BY MLONG	DATE 2004/06/11	MOLEX INCORPORATED	
	3 PLACES			± ---	± ---	± ---	APPROVED BY GGLEE	DATE 2004/06/11		DOCUMENT NO. SD-87916-001
2 PLACES	± 0.25	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	SHEET NO. 5 OF 5			
1 PLACE	± ---	± ---	± ---							
		ANGULAR ± 5 °								

9 8 7 6 5 4 3 2 1